

IFW

In re the Application of: Miwa KOZAWA et al.

Group Art Unit: 1752

Serial No.: 10/629,806

Examiner: LEE, SIN J

Filed: July 30, 2003

Confirmation No.: 9494

For: RESIST PATTERN THICKENING MATERIAL, PROCESS FOR

FORMING RESIST PATTERN, AND PROCESS FOR MANUFACTURING

SEMICONDUCTOR DEVICE

Attorney Docket No.: 030923

Customer Number: 38834

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

September 2, 2004

Sir:

In response to the Office Action dated June 3, 2004, please amend the above-identified application as follows:

<u>Amendments to the Claims</u> are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 8 of this paper.